Board Characteristics - 4 LAYER BOARD

1. Nominal FKM
2. Minimum trace width and clearance: 0.005"  
3. 1 oz copper for all power layers and for Signal 1, 2 (Top and Bottom)

4. All dimensions are given in inches unless specified otherwise.

5. Immersion gold over copper, with min. 96: 2.5-5.0 µm, Au: 0.05-0.2 µm

6. Soldermask on Component and Solder Sides.

7. 45 degree chamfer

8. FR4 tolerance 0.003

9. Interlayer spacing as specified

10. Trace Impedance: 50 Ohms +/- 10%